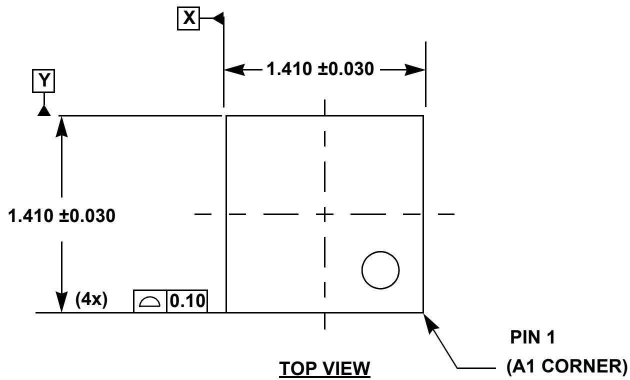
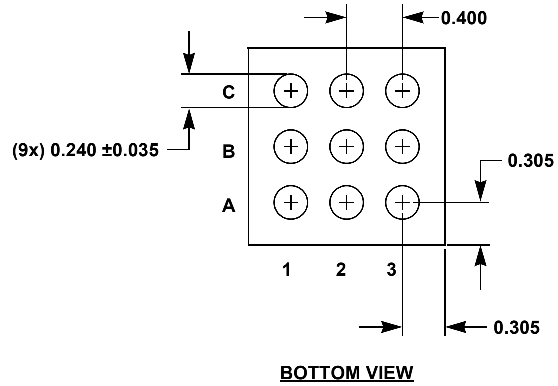
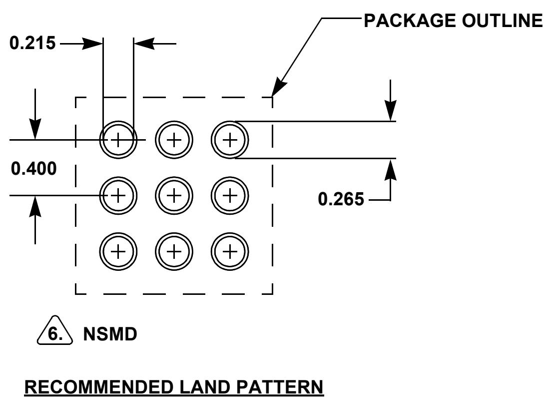
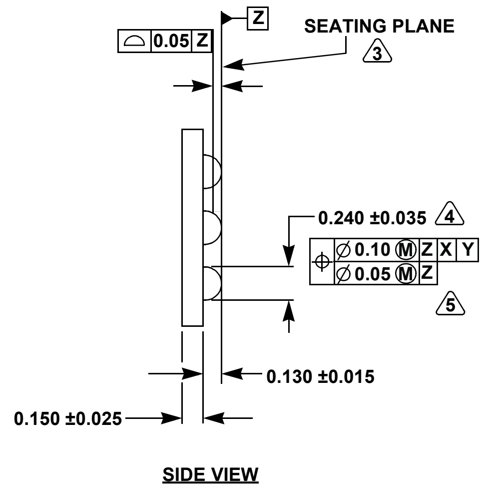
1. Package Outline Drawing

W3x3.9H
9 BALL 3x3 ARRAY ULTRA THIN WAFER LEVEL CHIP SCALE PACKAGE (WLCSP) 0.4mm Pitch
Rev 2, 11/17









NOTES:

1. All dimensions are in millimeters.
2. Dimensions and tolerance per ASME Y14.5 - 1994.
3. Primary datum Z and seating plane are defined by the spherical crowns of the bump.
4. Dimension is measured at the maximum bump diameter parallel to primary datum Z.
5. Bump position designation per JESD 95-1, SPP-010.
6. NSMD refers to non-solder mask defined pad design per Intersil tech brief TB451.